

**In the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently amended). An electronic circuit unit comprising:  
an alumina substrate;  
thin film circuit elements including capacitors, resistors, and inductance elements formed on the alumina substrate;  
thin film conducting patterns connected to the circuit elements formed on the alumina substrate; and  
a semiconductor bare chip mounted on the alumina substrate and wire bonded to the conducting pattern,  
wherein at least one of the capacitors ~~has an extension that is non-rectangular in shape formed from a plurality of rectangles and the extension projects from one side of another rectangle [ . ]~~ is comprised of two parallel plates disposed on either side of a dielectric material and whose perimeter has a non-rectangular shape.
2. (Original) The electronic circuit unit according to claim 1, wherein the non-rectangular shape has at least two rectangles that are combined together.
3. (Currently amended) The electronic circuit unit according to claim 1, wherein the non-rectangular capacitor is an earth-ground capacitor.
4. (Currently amended) The electronic circuit unit according to claim 2, wherein the non-rectangular capacitor is an earth-ground capacitor.
5. (Previously presented) An electronic circuit unit comprising thin film circuit elements including conducting patterns formed on an alumina substrate, a plurality of thin film capacitors formed on the alumina substrate so as to be connected to the conducting patterns, resistors, and inductance elements and a semiconductor bare chip having a transistor wire-bonded to the conducting patterns, wherein the conducting pattern has a connection land connected to an electrode of the transistor to be

grounded in a high frequency band, the capacitor has a plurality of ground capacitors grounded in the high frequency band, and one electrode of each of the plurality of capacitors is connected to the ground conducting pattern and the other electrode of each of the plurality of capacitors is connected to the connection land through the conducting patterns that are separated from each other.

6. (Original) The electronic circuit unit according to claim 5, wherein the plurality of ground capacitors are different from each other in size.

7. (Previously presented) The electronic circuit unit according to claim 5, wherein a part of the ground conducting pattern serves as the one electrode of each of the plurality of ground capacitors.

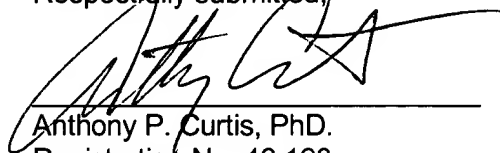
8. (Previously presented) The electronic circuit unit according to claim 6, wherein a part of the ground conducting pattern serves as the one electrode of each of the plurality of ground capacitors.

9. (New) The electronic circuit unit according to claim 3, wherein a portion of the thin film conducting pattern formed on the substrate and disposed on one side of the dielectric material serves as the one electrode of a ground capacitor.

10. (New) The electronic circuit as in claim 1, wherein each parallel plate of the non-rectangular capacitor is comprised of a plurality of contiguous rectangular areas, at least one of which has different linear dimensions or orientation.

11. (New) The electronic circuit unit according to claim 10, wherein the non-rectangular capacitor is a ground capacitor.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'Anthony P. Curtis', is written over a horizontal line.

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